

Features

- I_{off} supports partial-power-down mode operation
- Edge-rate control circuitry for significantly improved noise characteristics
- Typical output skew < 250 ps
- ESD > 2000V
- TSSOP (19.6-mil pitch) and SSOP (25-mil pitch) packages
- Industrial temperature range of -40°C to $+85^{\circ}\text{C}$
- $V_{CC} = 5\text{V} \pm 10\%$

CY74FCT16240T Features:

- 64 mA sink current, 32 mA source current
- Typical V_{OLP} (ground bounce) < 1.0V at $V_{CC} = 5\text{V}$, $T_A = 25^{\circ}\text{C}$

CY74FCT162240T Features:

- Balanced output drivers: 24 mA
- Reduced system switching noise
- Typical V_{OLP} (ground bounce) < 0.6V at $V_{CC} = 5\text{V}$, $T_A = 25^{\circ}\text{C}$

Functional Description

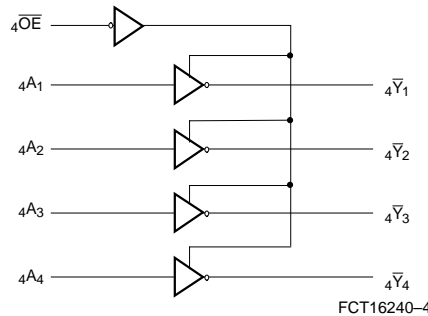
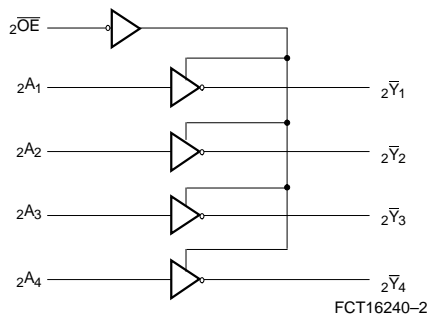
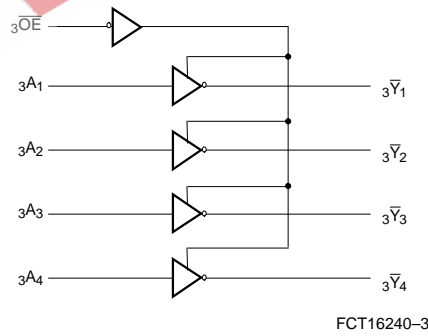
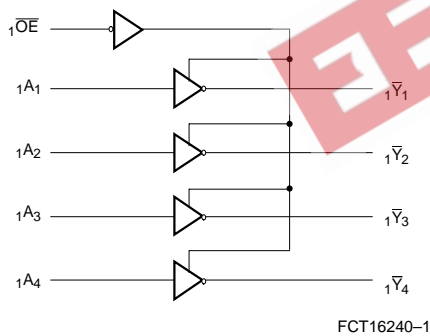
These 16-bit buffer/line drivers are used in memory driver, clock driver, or other bus interface applications, where high speed and low power are required. With flow-through pinout and small shrink packaging, board layout is simplified. The three-state controls are designed to allow 4-, 8-, or 16-bit operation.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

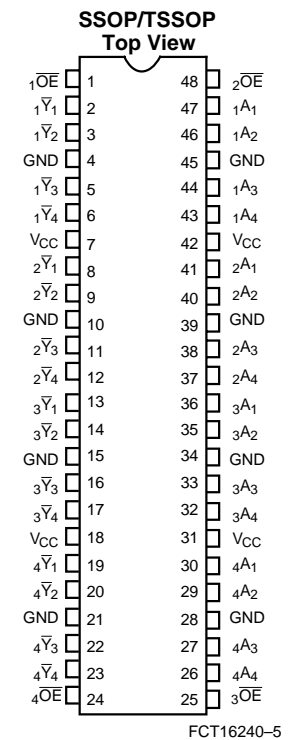
The CY74FCT16240T is ideally suited for driving high-capacitance loads and low-impedance backplanes.

The CY74FCT162240T has 24-mA balanced output drivers with current limiting resistors in the outputs. This reduces the need for external terminating resistors and provides for minimal undershoot and reduced ground bounce. The CY74FCT162240T is ideal for driving transmission lines.

Logic Block Diagrams



Pin Configuration



Pin Summary

Name	Description
\overline{OE}	Three-State Output Enable Inputs (Active LOW)
A	Data Inputs
\overline{Y}	Three-State Outputs

Function Table^[1]

Inputs		Outputs
\overline{OE}	A	\overline{Y}
L	L	H
L	H	L
H	X	Z

Maximum Ratings^[2, 3]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature Com'l. -55°C to +125°C

Ambient Temperature with

Power Applied..... Com'l. -55°C to +125°C

DC Input Voltage -0.5V to +7.0V

DC Output Voltage..... -0.5V to +7.0V

DC Output Current

(Maximum Sink Current/Pin) -60 to +120 mA

Power Dissipation 1.0W

Static Discharge Voltage

(per MIL-STD-883, Method 3015) >2001V

Operating Range

Range	Ambient Temperature	V _{CC}
Industrial	-40°C to +85°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Typ. ^[4]	Max.	Unit
V _{IH}	Input HIGH Voltage		2.0			V
V _{IL}	Input LOW Voltage				0.8	V
V _H	Input Hysteresis ^[5]			100		mV
V _{IK}	Input Clamp Diode Voltage	V _{CC} = Min., I _{IN} = -18 mA		-0.7	-1.2	V
I _{IH}	Input HIGH Current	V _{CC} = Max., V _I = V _{CC}			±1	µA
I _{IH}	Input HIGH Current	V _{CC} = Max., V _I = V _{CC}			±1	µA
I _{IL}	Input LOW Current	V _{CC} = Max., V _I = GND			±1	µA
I _{IL}	Input LOW Current	V _{CC} = Max., V _I = GND			±1	µA
I _{OZH}	High Impedance Output Current (Three-State Output pins)	V _{CC} = Max., V _{OUT} = 2.7V			±1	µA
I _{OZL}	High Impedance Output Current (Three-State Output pins)	V _{CC} = Max., V _{OUT} = 0.5V			±1	µA
I _{OS}	Short Circuit Current ^[6]	V _{CC} = Max., V _{OUT} = GND	-80	-140	-200	mA
I _O	Output Drive Current ^[6]	V _{CC} = Max., V _{OUT} = 2.5V	-50		-180	mA
I _{OFF}	Power-Off Disable	V _{CC} = 0V, V _{OUT} ≤ 4.5V ^[7]			±1	µA

Output Drive Characteristics for CY74FCT16240T

Parameter	Description	Test Conditions	Min.	Typ. ^[4]	Max.	Unit
V _{OH}	Output HIGH Voltage	V _{CC} = Min., I _{OH} = -3 mA	2.5	3.5		V
		V _{CC} = Min., I _{OH} = -15 mA	2.4	3.5		V
		V _{CC} = Min., I _{OH} = -32 mA	2.0	3.0		V
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 64 mA		0.2	0.55	V

Notes:

1. H = HIGH Voltage Level. L = LOW Voltage Level. X = Don't Care. Z = High Impedance.
2. Operation beyond the limits set forth may impair the useful life of the device. Unless noted, these limits are over the operating free-air temperature range.
3. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
4. Typical values are at V_{CC}=5.0V, T_A= +25°C ambient.
5. This parameter is specified but not tested.
6. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.
7. Tested at +25°C.

Output Drive Characteristics for CY74FCT162240T

Parameter	Description	Test Conditions	Min.	Typ. ^[4]	Max.	Unit
I _{ODL}	Output LOW Current ^[6]	V _{CC} = 5V, V _{IN} = V _{IH} or V _{IL} , V _{OUT} = 1.5V	60	115	150	mA
I _{ODH}	Output HIGH Current ^[6]	V _{CC} = 5V, V _{IN} = V _{IH} or V _{IL} , V _{OUT} = 1.5V	-60	-115	-150	mA
V _{OH}	Output HIGH Voltage	V _{CC} = Min., I _{OH} = -24 mA	2.4	3.3		V
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 24 mA		0.3	0.55	V

Capacitance^[5] (T_A = +25°C, f = 1.0 MHz)

Parameter	Description	Test Conditions	Typ. ^[4]	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	4.5	6.0	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	5.5	8.0	pF

Power Supply Characteristics

Parameter	Description	Test Conditions	Typ. ^[4]	Max.	Unit	
I _{CC}	Quiescent Power Supply Current	V _{CC} =Max. V _{IN} ≤0.2V, V _{IN} ≥V _{CC} -0.2V	5	500	μA	
ΔI _{CC}	Quiescent Power Supply Current (TTL inputs HIGH)	V _{CC} =Max. V _{IN} =3.4V ^[8]	0.5	1.5	mA	
I _{CCD}	Dynamic Power Supply Current ^[9]	V _{CC} =Max., One Input Toggling, 50% Duty Cycle, Outputs Open, \overline{OE} =GND	60	100	μA/MHz	
I _C	Total Power Supply Current ^[10]	V _{CC} =Max., f ₁ =10 MHz, 50% Duty Cycle, Outputs Open, One Bit Toggling, \overline{OE} =GND	V _{IN} =V _{CC} or V _{IN} =GND	0.6	1.5	mA
			V _{IN} =3.4V or V _{IN} =GND	0.9	2.3	mA
		V _{CC} =Max., f ₁ =2.5 MHz, 50% Duty Cycle, Outputs Open, Sixteen Bits Toggling, \overline{OE} =GND	V _{IN} =V _{CC} or V _{IN} =GND	2.4	4.5 ^[11]	mA
			V _{IN} =3.4V or V _{IN} =GND	6.4	16.5 ^[11]	mA

Notes:

8. Per TTL driven input (V_{IN}=3.4V); all other inputs at V_{CC} or GND.
9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
10. I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}
I_C = I_{CC} + ΔI_{CC}D_HN_T + I_{CCD}(f₀/2 + f₁N₁)
I_{CC} = Quiescent Current with CMOS input levels
ΔI_{CC} = Power Supply Current for a TTL HIGH input (V_{IN}=3.4V)
D_H = Duty Cycle for TTL inputs HIGH
N_T = Number of TTL inputs at D_H
I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
f₀ = Clock frequency for registered devices, otherwise zero
f₁ = Input signal frequency
N₁ = Number of inputs changing at f₁
All currents are in milliamps and all frequencies are in megahertz.
11. Values for these conditions are examples of the I_{CC} formula. These limits are specified but not tested.

Switching Characteristics Over the Operating Range^[12]

Parameter	Description	CY74FCT16240AT		CY74FCT162240CT		Unit	Fig. No. ^[13]
		Min.	Max.	Min.	Max.		
t _{PLH} t _{PHL}	Propagation Delay Data to Output	1.5	4.8	1.5	4.3	ns	1, 2
t _{PZH} t _{PZL}	Output Enable Time	1.5	6.2	1.5	5.8	ns	1, 7, 8
t _{PHZ} t _{PLZ}	Output Disable Time	1.5	5.6	1.5	5.2	ns	1, 7, 8
t _{SK(O)}	Output Skew ^[14]		0.5		0.5	ns	—

Note:

12. Minimum limits are specified but not tested on Propagation Delays.
13. See "Parameter Measurement Information" in the General Information section.
14. Skew between any two outputs of the same package switching in the same direction. This parameter is ensured by design.

Ordering Information CY74FCT16240

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.8	CY74FCT16240ATPVC/PVCT	O48	48-Lead (300-Mil) SSOP	Industrial

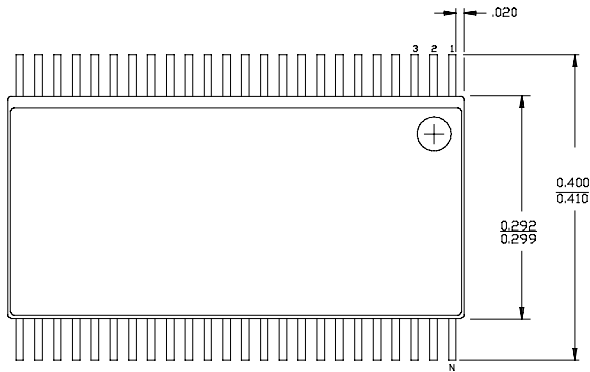
Ordering Information CY74FCT162240

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.3	74FCT162240CTPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT162240CTPVC	O48	48-Lead (300-Mil) SSOP	
	74FCT162240CTPVCT	O48	48-Lead (300-Mil) SSOP	

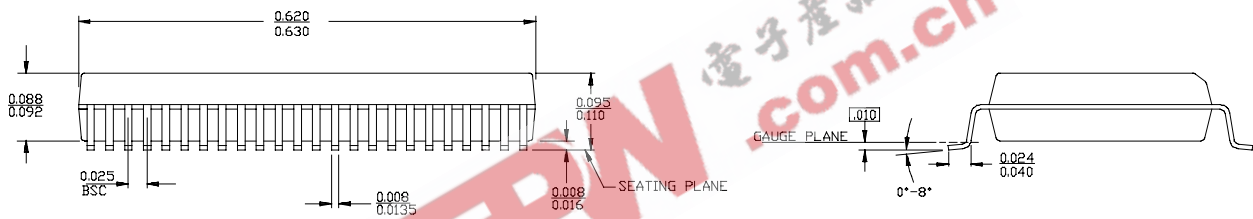
Document #: 38-00395-C

Package Diagrams

48-Lead Shrink Small Outline Package O48

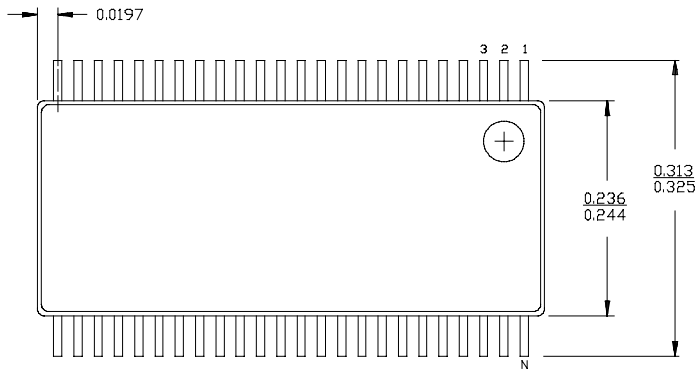


DIMENSIONS IN INCHES MIN.
MAX.

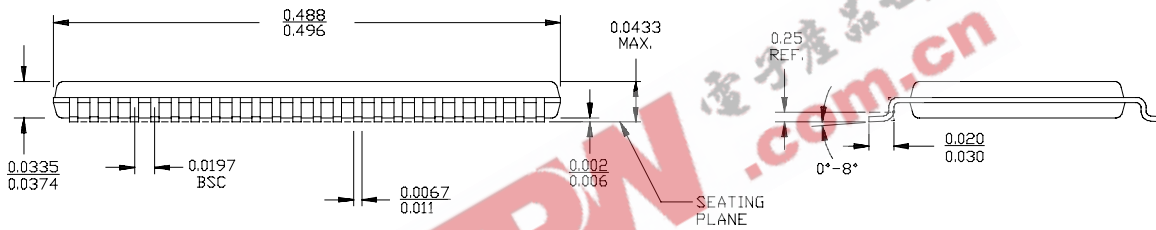


Package Diagrams

48-Lead Thin Shrunken Small Outline Package



DIMENSIONS IN INCHES MIN.
MAX.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74FCT162240ATPACT	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT162240CTPACT	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT162240CTPVCT	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT162240ETPACT	OBSOLETE	TSSOP	DGG	48		TBD	Call TI	Call TI
74FCT162240ETPVCT	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
74FCT16240ATPACTE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT162240CTPVC	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT162240ETPAC	OBSOLETE	TSSOP	DGG	48		TBD	Call TI	Call TI
CY74FCT162240ETPVC	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
CY74FCT16240ATPACT	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT16240ATPVC	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT16240ATPVCT	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT16240ETPVC	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
CY74FCT16240ETPVCT	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
FCT162240ATPACTE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
FCT162240CTPACTE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited

information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

EEPW 电子產品世界
.com.cn

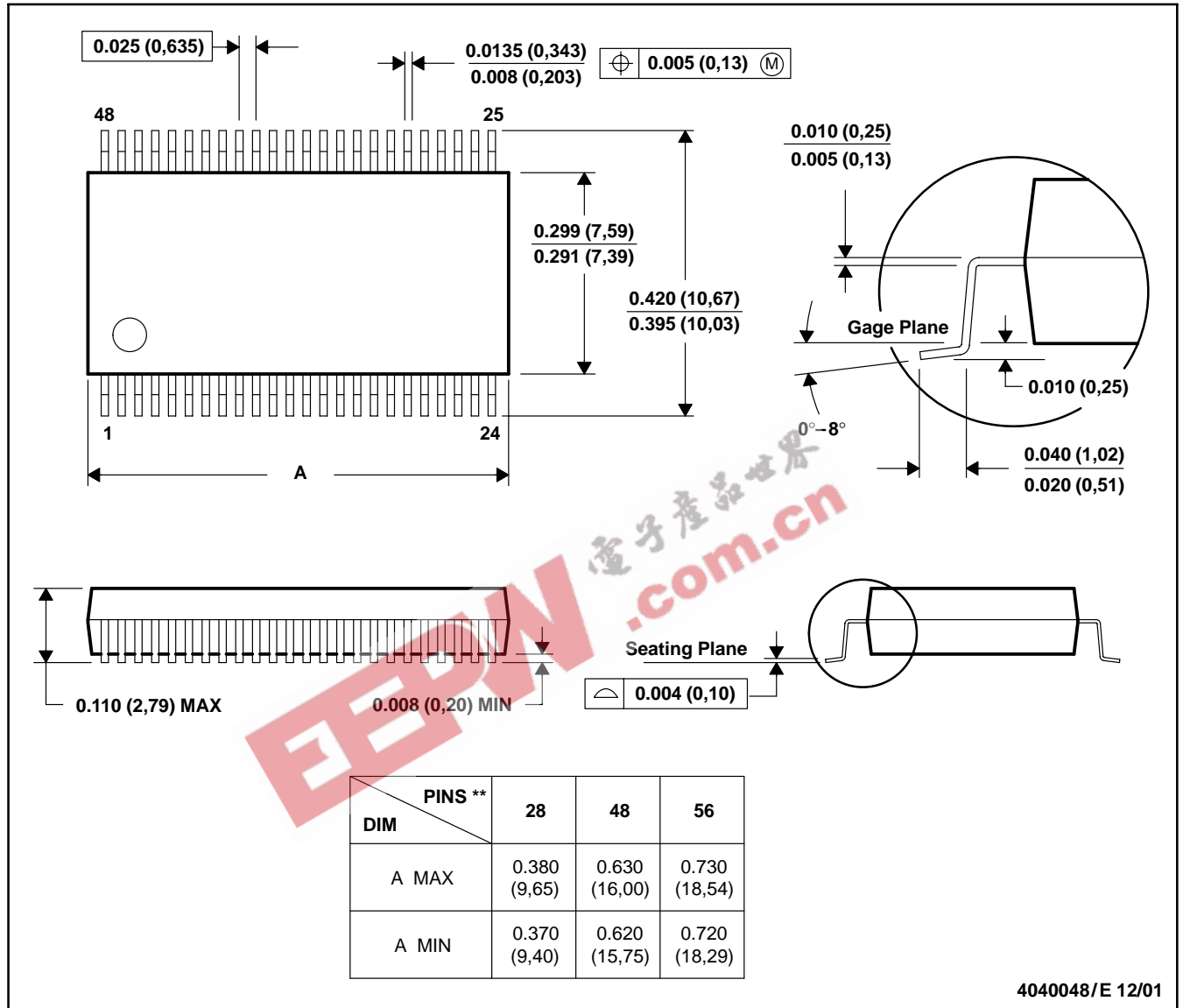
MECHANICAL DATA

MSS0001C – JANUARY 1995 – REVISED DECEMBER 2001

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

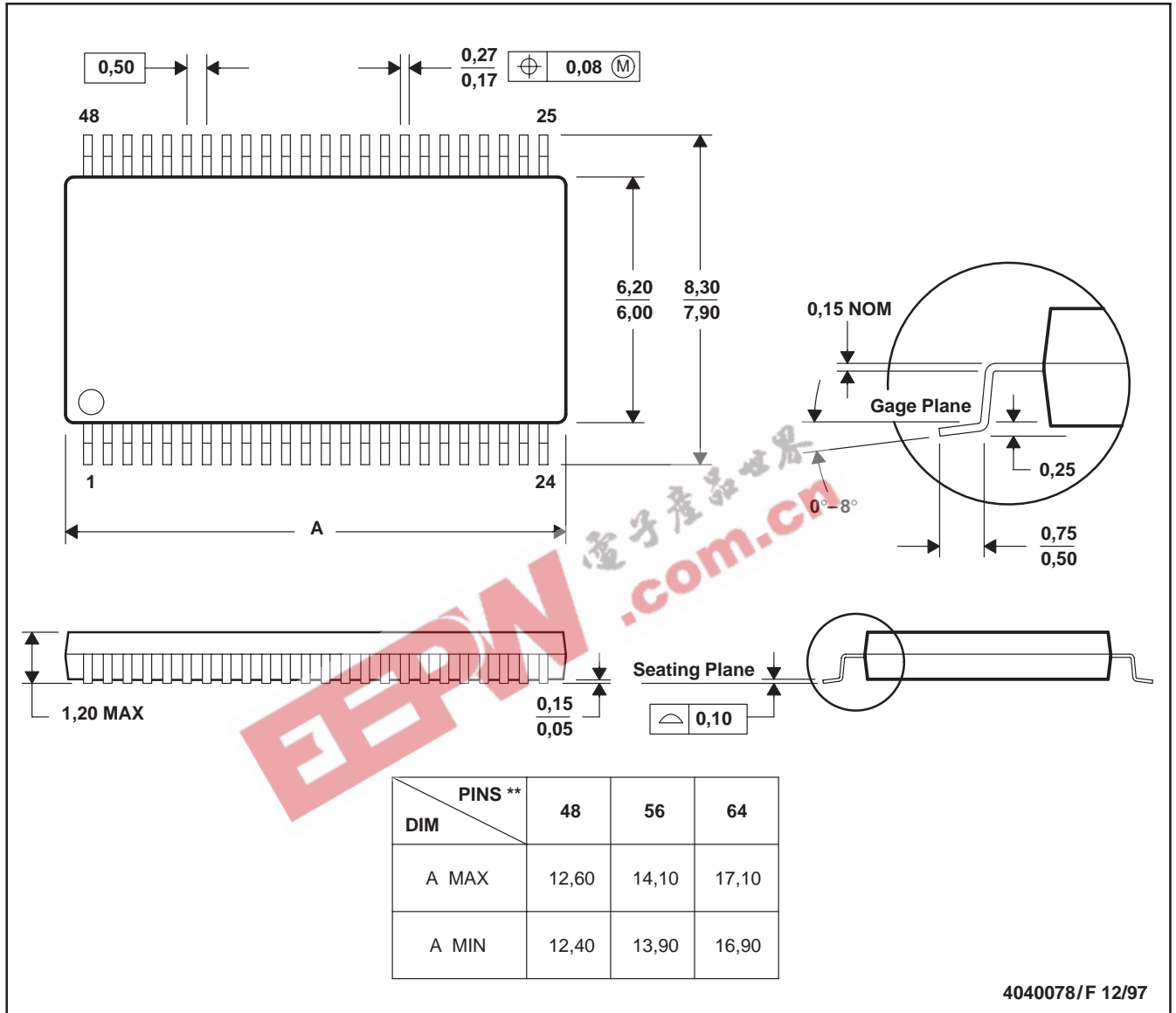
MECHANICAL DATA

MTSS003D – JANUARY 1995 – REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold protrusion not to exceed 0,15.
 - D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265